

### **International Conference on Applied Superconductivity and Electromagnetic Devices**

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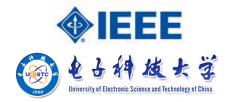
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# ASEMD2009

## 2009 International Conference on Applied Superconductivity and ElectroMagnetic Devices (ASEMD09)

### 25-27 September 2009, Chengdu, China



The IEEE 2009 International Conference on Applied Superconductivity and Electromagnetic Devices (ASEMD09) will be held on 25-27 September 2009 in Chengdu, China. ASEMD09, principally sponsored by IEEE and University of Electronic Science and Technology of China, aims to be a premier conference on applied superconductivity and electromagnetic devices. It provides a forum for researchers and experts in the relevant fields to discuss and share ideas, present results, reflect on past experiences and discuss future developments.



**Scope:** ASEMD'09 invites submissions on the recent and original research and industrial developments in universities and high-tech companies worldwide in the areas of applied superconductivity and electromagnetic devices. The scope of the conference includes but not limited to the following topics:

- Strong Current and Large Scale Applied Superconductivity
- Superconducting Electronics
- Superconducting and Electromagnetic Materials
- Electromagnetic Devices
- Electric Power Devices
- Electrical Machines
- Energy Efficiency Devices
- Power Electronic Devices and Circuits
- Advanced Devices of Control and Measurement

**Submission and Publication:** Prospective authors are invited to submit a two-page digest on their original, unpublished contributions. The two-page digest should consist of the paper title, names of all authors, organization, abstract, preferred topic areas, main body and the contact information (phone, fax and email) of the corresponding author. The digest should



include the key contributions of authors in sufficient detail for undergoing a peer review process. A template for the digest will be available at the conference website http://www.asemd.org or http://www.asemd.org.cn. All digests and papers will be peer-reviewed by at least three independent reviewers. All the accepted full papers will be published by the IEEE conference proceedings (IEEE Catalog Number: CFP0920G; ISBN: 978-1-

4244-3687-3; Library of Congress: 2008911779), and will be included in IEEE Xplore and indexed by EI.

### **Important Dates:**

Abstract Submission Due to 15 April 2009 Announcement of acceptance and invitation for paper submission starting from 15 May 2009

### All papers should be submitted by either of the following ways:

- Online submission on this website: http://www.asemd.org or http://www.asemd.org.cn
- Email to asemd@sina.com, sem08@sina.com, asemd@uestc.edu.cn or journal@uestc.edu.cn

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